

Title (en)

CATIONIC ELECTRODEPOSITION COATING COMPOSITION

Title (de)

ZUSAMMENSETZUNG ZUR ELEKTROLYTISCHEN KATHODENABSCHIEDUNGSBESCHICHTUNG

Title (fr)

COMPOSITION DE REVÊTEMENT POUR ÉLECTRODÉPOSITION CATIONIQUE

Publication

**EP 3998316 A1 20220518 (EN)**

Application

**EP 20836845 A 20200703**

Priority

- JP 2019129248 A 20190711
- JP 2020026266 W 20200703

Abstract (en)

Provided is a cationic electrodeposition coating composition having good anti-cratering performance. A cationic electrodeposition coating composition comprising a coating film-forming resin (A), a metal compound (B) containing a trivalent metal element, and a silicone compound (C), wherein a content of the metal compound (B) is 0.03 parts by mass or more and less than 4 parts by mass in terms of a metal element based on 100 parts by mass of a resin solid content of the coating film-forming resin (A), and a content of the silicone compound (C) is 0.005 parts by mass or more and 4.5 parts by mass or less based on 100 parts by mass of the resin solid content of the coating film-forming resin (A).

IPC 8 full level

**C09D 5/44** (2006.01); **C09D 7/61** (2018.01); **C09D 7/65** (2018.01); **C09D 201/00** (2006.01)

CPC (source: CN EP US)

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Designated contracting state (EPC)

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Designated extension state (EPC)

BA ME

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